

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application: Rajeev Joshi et al. Serial No.: 10/618,113 Filed: July 11, 2003 For: WAFER-LEVEL CHIP SCALE PACKAGEA AND METHOD FOR FABRICATING AND USING THE SAME	Confirmation No. 8697 Group Art Unit: 2891 Examiner: David A Zarneke
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Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

REQUEST FOR RECONSIDERATION UNDER 37 C.F.R. § 1.111

In response to the Office Action dated May 15, 2007, Applicants request reconsideration of this application in light of the following remarks. Applicants have concurrently filed a petition for a one-month extension of time to extend the period of response to September 15, 2007.

Remarks begin on page 2 of this paper.